

Feature	2 Layer
Number of layers	2 layers
Materials	FR-4 standard, FR-4 high performance, FR-4 halogen-free.
Copper thickness (finished)	26,2µm – 108,6µm, advanced 330µm
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	0.40mm – 3.2mm
Maximum dimensions	546mm x 622mm, advanced 600mm x 1100mm
Surface finishes available	HASL (SnPb), LF HASL (SnNiCu), OSP, ENIG, Immersion tin, Immersion silver, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.15mm

Feature	Multilayer
Number of layers	4 – 24 layers
Materials	High performance FR4, halogen-free FR4, low loss and low Dk materials
Copper thickness (finished)	26,2µm – 108,6µm, advanced 330µm
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	0.40mm – 7.0mm
Maximum dimensions	546mm x 622mm, advanced 600mm x 1100mm
Surface finishes available	HASL (SnPb), LF HASL (SnNiCu), OSP, ENIG, Immersion Tin, Immersion Silver, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.15mm

Feature	Rigid - Flex
Number of layers	4-12 layers
Materials	RA copper, HTE copper, FR-4, polyimide, adhesive
Copper thickness (finished)	26,2µm – 108,6µm, advanced 330µm
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	0.4mm - 3mm
PCB thickness in flex section	0.05mm - 0.8mm
Maximum dimensions	457mm x 610mm
Surface finishes available	ENIG, OSP Immersion tin, Immersion silver
Minimum mechanical drill	0.15mm

Feature	Flexible
Number of layers	1 – 6L
Materials	Polyimide, Polyester
Profile method	Laser cutting, punching, rout
Copper thickness (finished)	18µm – 70µm
Minimum track and gap	0.075mm / 0.075mm
PCB thickness	0.05mm – 0.80mm
Maximum dimensions	450mm x 610mm
Surface finishes available	OSP, ENIG, Immersion tin, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.15mm

Feature	IMS
Number of layers	1 – 4 layers
Materials	Aluminium & copper plates. FR-4, PTFE, thermal dielectrics.
Dielectric thickness	0.05mm – 0.20mm
Thermal conductivity	1-12 W/m/K
Profile method	Punching, routing
Copper thickness (finished)	35µm – 140µm
Minimum track and gap	0.10mm / 0.10mm
Metal core thickness	0.40mm – 3.20mm
Maximum dimensions	550mm x 700mm
Surface finishes available	HASL, LF HASL, OSP, ENIG, Immersion tin, Immersion silver
Minimum mechanical drill	0.30mm

Feature	Single side
Number of layers	1 layer
Materials	CEM1, FR4, CEM3
Copper thickness (finished)	18µm – 105µm
Minimum track and gap	0.10mm / 0.10mm
PCB thickness	0.63mm – 3,2mm
Maximum dimensions	546mm x 622mm
Surface finishes available	HASL (SnPb), LF HASL (SnNiCu), OSP, ENIG, Immersion tin, Immersion silver, Electrolytic gold, Gold fingers
Minimum mechanical drill	0.2mm